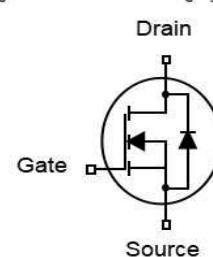


Features

- N-Channel
- Low FOM $R_{DS(on)} \times Q_{gd}$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant
- 100% EAS Tested

V_{DS}	60	V
$R_{DS(on),TYP} @ V_{GS}=10V$	25	mΩ
$R_{DS(on),TYP} @ V_{GS}=4.5V$	32	mΩ
I_D	20	A

DFN5x6



Part ID	Package Type	Marking	Packing
ZT25N06G	DFN5x6	ZT25N06G	5000pcs/Reel

Absolute Maximum Ratings $T_A = 25^\circ C$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_c=25^\circ C$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 3)	$T_c=25^\circ C$	80	A
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous (Note 2)	$T_c=25^\circ C$	20	A
		$T_c=100^\circ C$	14	A
P_D	Maximum Power Dissipation	23	W	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	5.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	55	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 1)	48	mJ	



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

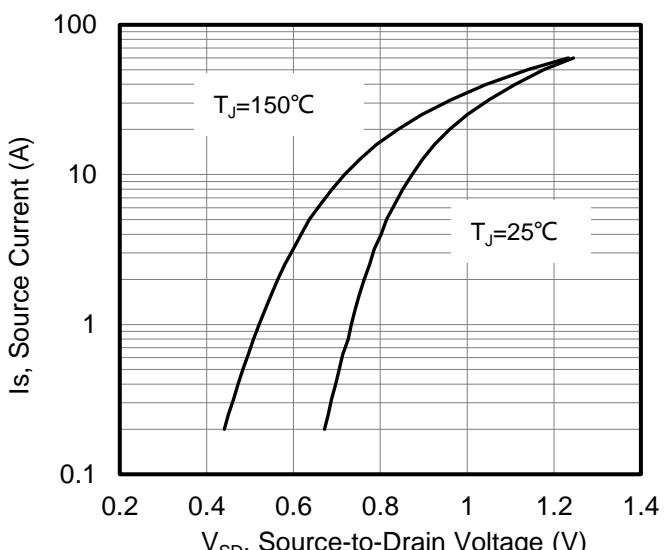
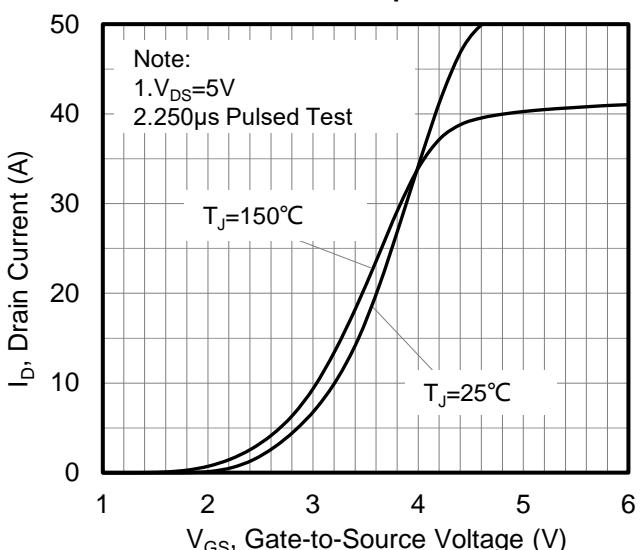
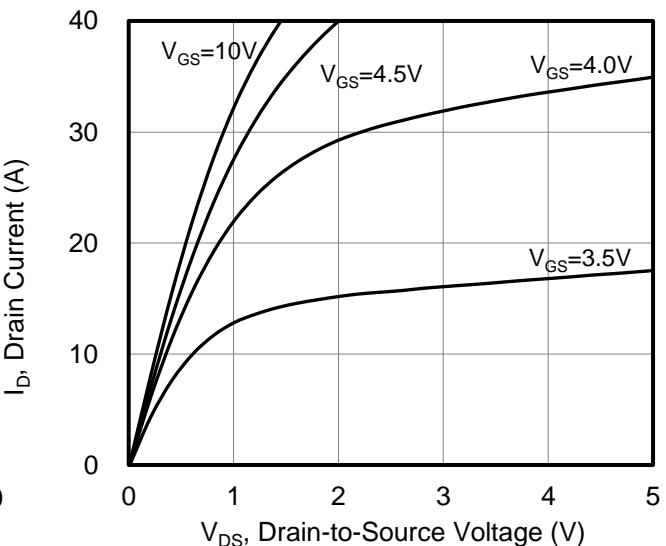
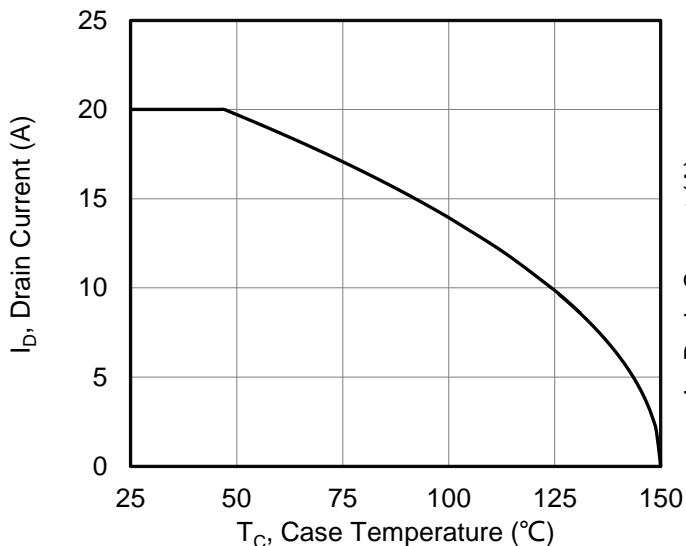
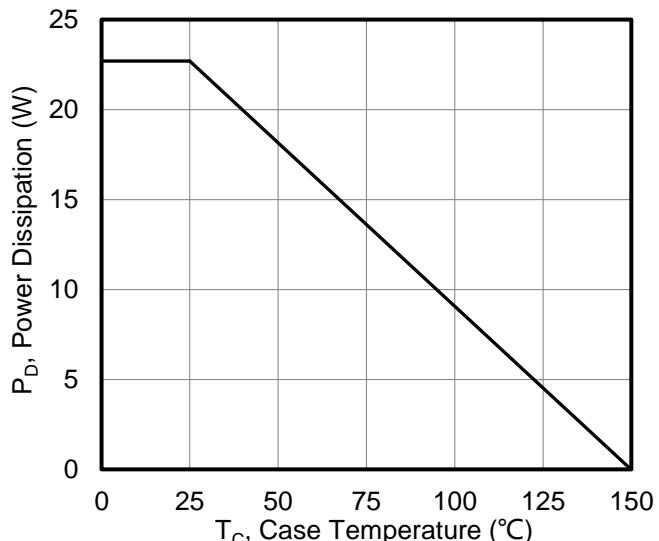
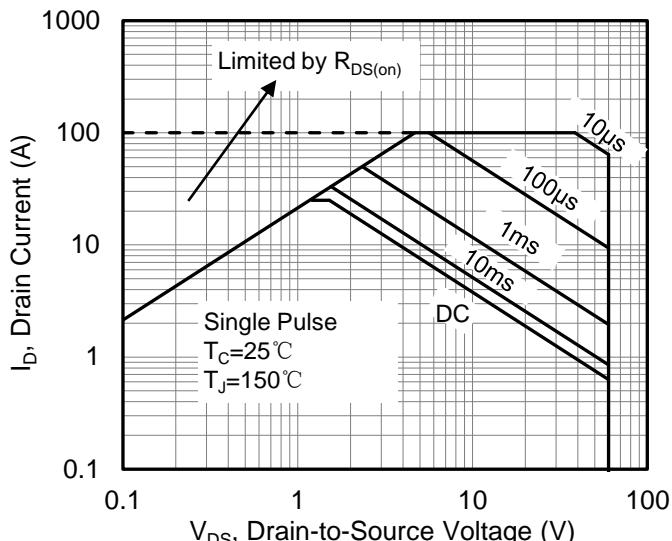
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60	--	--	V
I_{DS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
I_{GS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.8	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	25	30	$\text{m}\Omega$
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=10\text{A}$	--	32	41	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1056	--	pF
C_{oss}	Output Capacitance		--	62	--	pF
C_{rss}	Reverse Transfer Capacitance		--	52	--	pF
R_g	Gate Resistance	f=1MHz	--	1.6	--	Ω
Q_g	Total Gate Charge	$V_{DS}=30\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$	--	25	--	nC
Q_{gs}	Gate-Source Charge		--	5.5	--	nC
Q_{gd}	Gate-Drain Charge		--	5.1	--	nC
$V_{plateau}$	Gate plateau voltage		--	4.0	--	V
Switching Characteristics (Note 2)						
$T_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}, I_D=20\text{A}, R_G=3.0\Omega, V_{GS}=10\text{V}$	--	8.2	--	ns
T_r	Turn-on Rise Time		--	8.3	--	ns
$T_{d(off)}$	Turn-Off Delay Time		--	35	--	ns
T_f	Turn-Off Fall Time		--	5.1	--	ns
Source-Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
I_s	Diode Forward Current		--	--	20	A
V_{SD}	Forward on voltage	$I_s=20\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V
T_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_F=20\text{A}, V_{GS}=0\text{V}, dI/dt=100\text{A}/\mu\text{s}$	--	18	--	ns
Q_{rr}	Reverse Recovery Charge		--	13	--	μC

Notes:

1. $L=0.5\text{mH}, V_{DD}=30\text{V}$, Start $T_J=25^\circ\text{C}$.
2. Limited by maximum junction temperature.
3. Repetitive Rating: Pulse width limited by maximum junction temperature.



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted





Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

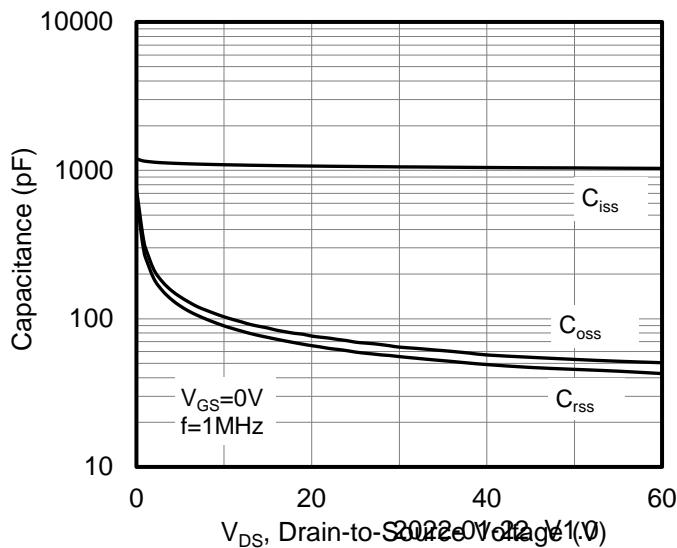


Figure 7. Capacitance Characteristics

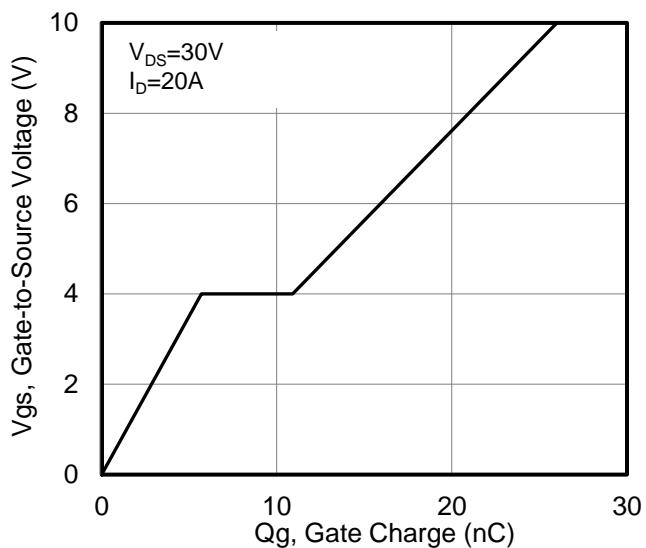


Figure 10. Typical Gate Charge vs Gate to Source Voltage

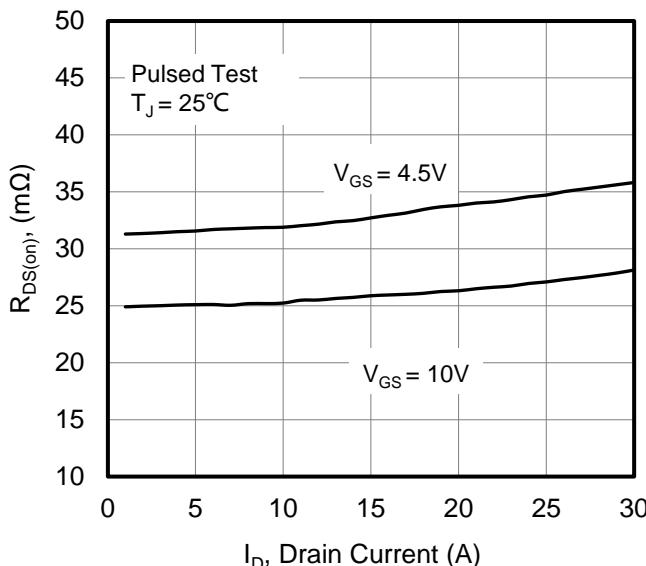


Figure 8. Drain-to-Source On Resistance vs Drain Current

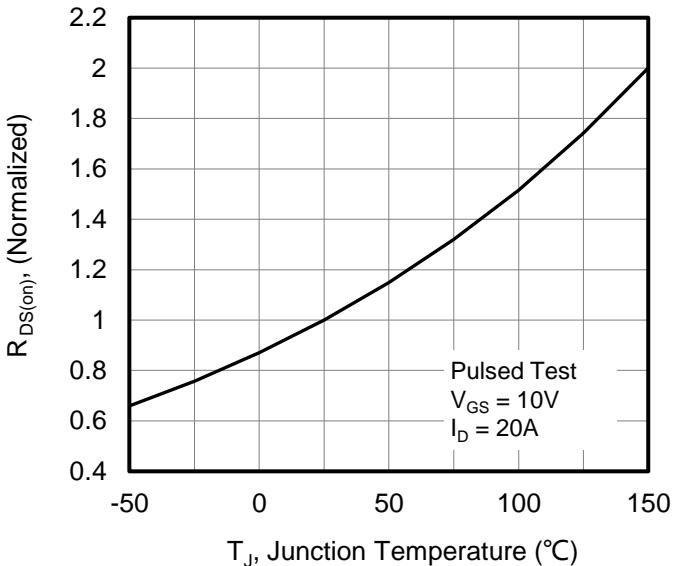


Figure 11. Normalized On Resistance vs Junction Temperature

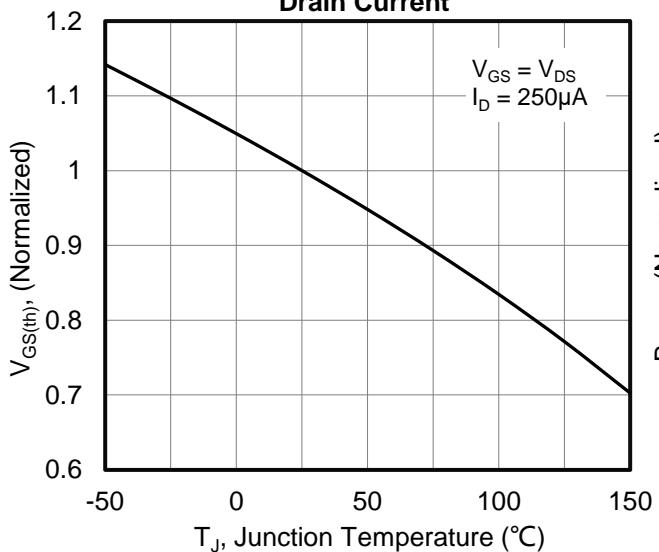


Figure 9. Normalized Threshold Voltage vs Junction Temperature

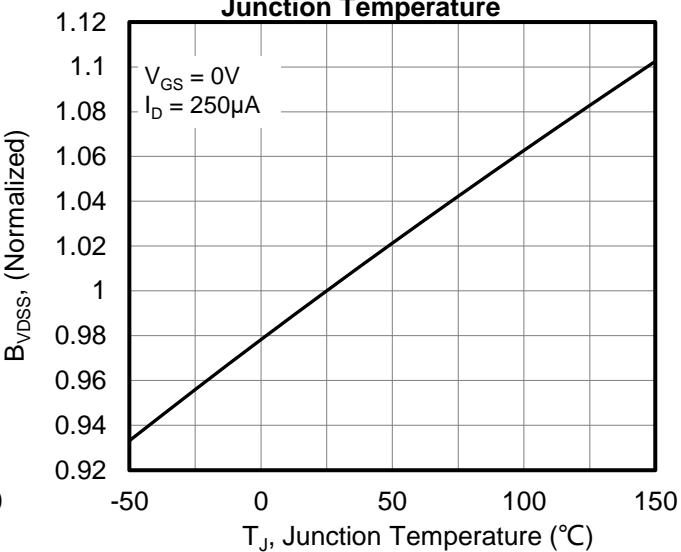


Figure 12. Normalized Breakdown Voltage vs Junction Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

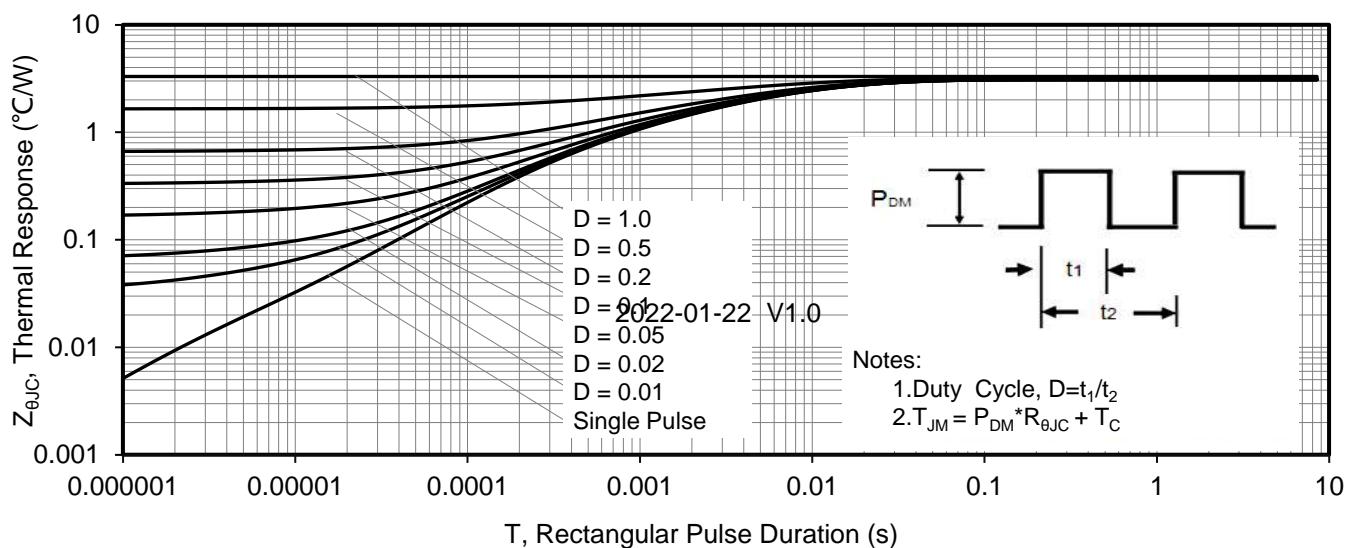
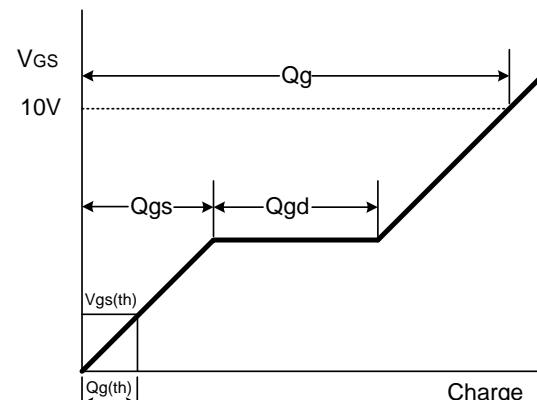
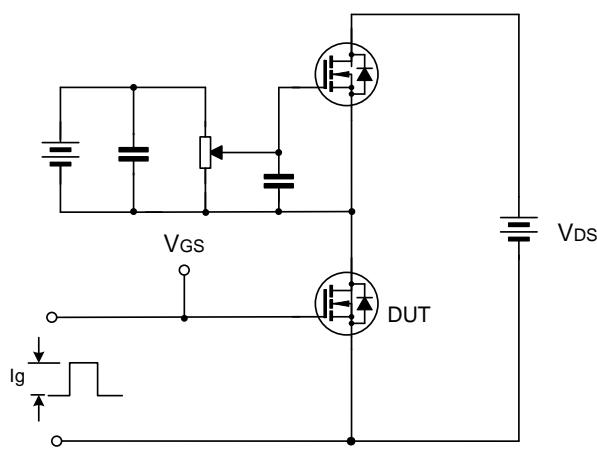


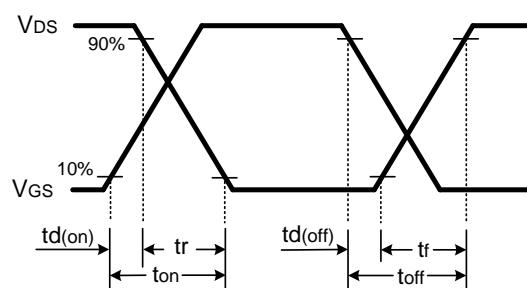
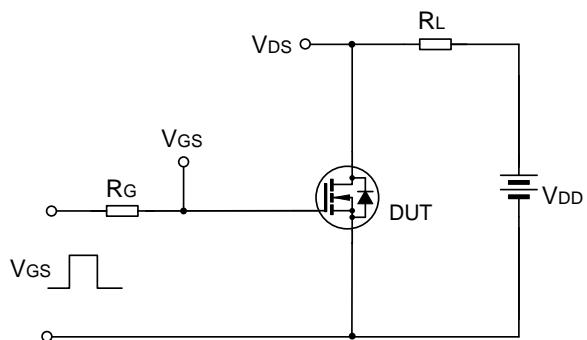
Figure 13. Maximum Effective Thermal Impedance, Junction to Case



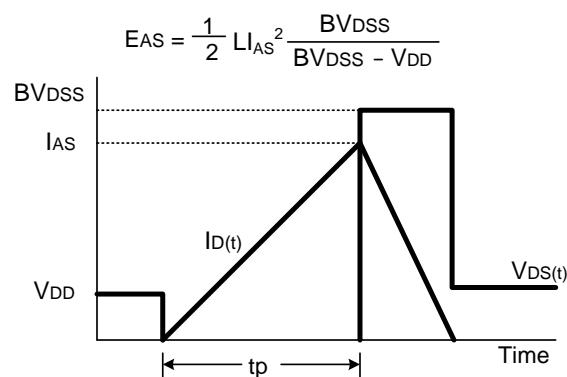
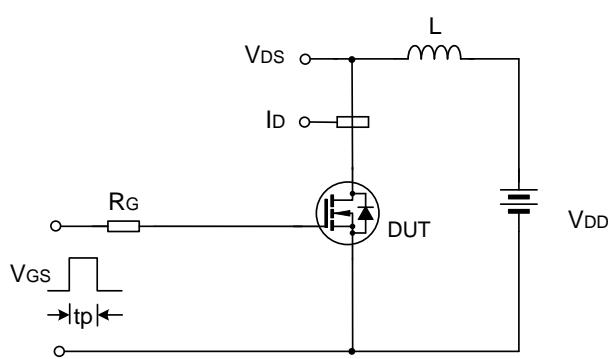
Test Circuit and Waveform



Gate Charge Test Circuit & Waveform



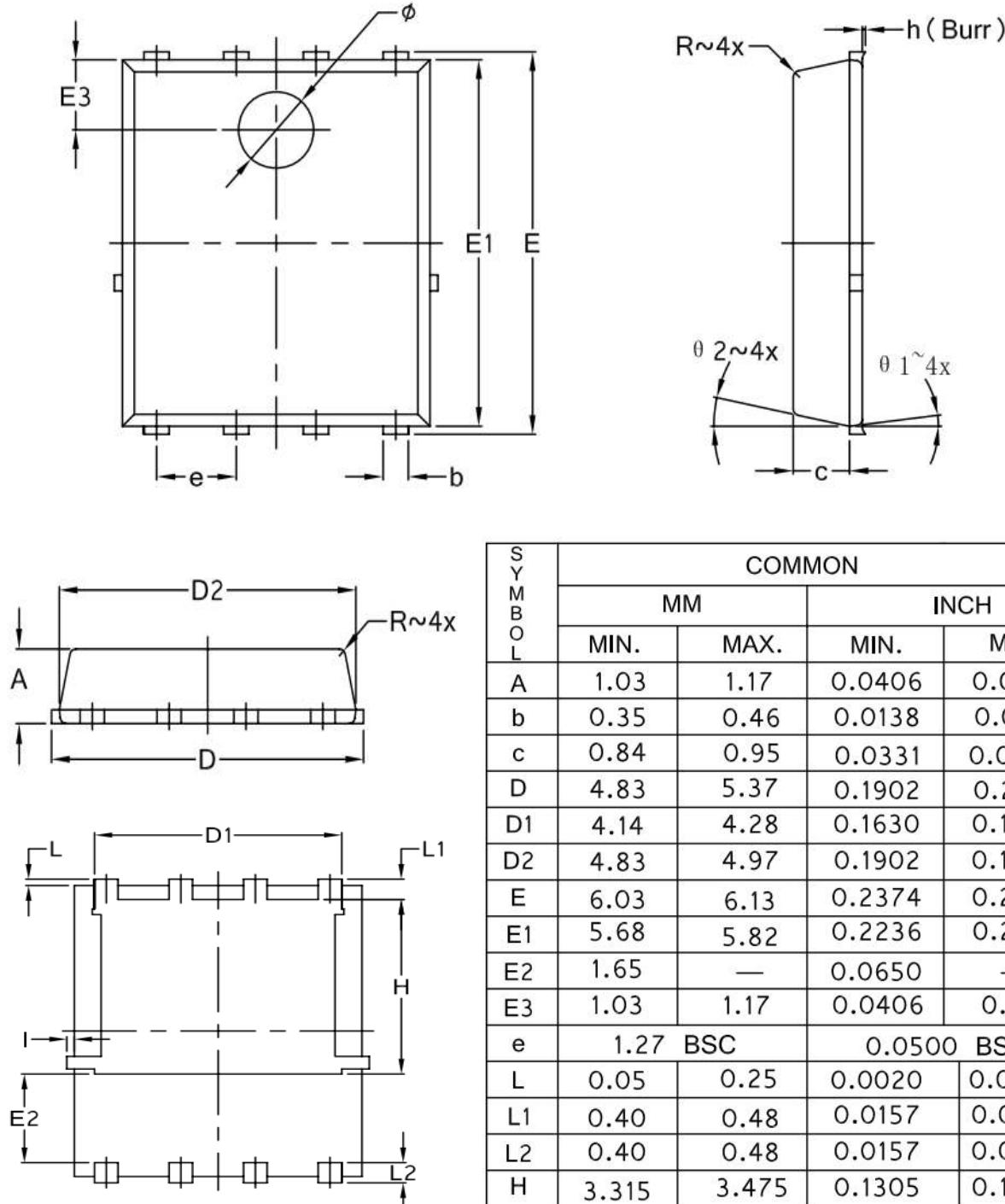
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Circuit & Waveforms



DFN5x6-8L Package Information



Customer Service

Sales and Service:

zj@ztasemi.com